

	Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s	E r r o r s
1	BRS	410	("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum)	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 18:16			0
2	BRS	410	("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum)	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 16:12			0
3	BRS	53835	PEG amd (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 16:12			0
4	BRS	0	PEG and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 16:12			0
5	BRS	0	sorbitol and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 16:13			0
6	BRS	0	sorbitol and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 16:13			0
7	BRS	30	("Polyvinyl alcohol" or "polyvinyl acetate" or (polyethylene adj2 polymer) or sobitol or glycerol or glycerin or polyacrylamind or "ethylene glycol" or "diethylene glycol" or "polyethylene glycol") and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 16:54			0

	Type	Hits	Search Text	DBs	Time Stamp	Com ments	Er ro r D ef in iti on	Er ro rs
8	BRS	54	("Polyvinyl alcohol" or "polyvinyl acetate" or (polyethylene adj2 polymer) or sobitol or glycerol or glycerin or polyacrylamind or "ethylene glycol" or "diethylene glycol" or "polyethylene glycol" or surfactant) and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 17:30			0
9	BRS	24	((("Polyvinyl alcohol" or "polyvinyl acetate" or (polyethylene adj2 polymer) or sobitol or glycerol or glycerin or polyacrylamind or "ethylene glycol" or "diethylene glycol" or "polyethylene glycol" or surfactant) and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum)))) not ((("Polyvinyl alcohol" or "polyvinyl acetate" or (polyethylene adj2 polymer) or sobitol or glycerol or glycerin or polyacrylamind or "ethylene glycol" or "diethylene glycol" or "polyethylene glycol") and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 16:40			0
10	BRS	71	("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum) same (SiO2 or "silicon dioxide")	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 17:14			0

	Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s	E r r o r s
11	BRS	9	("glycerol ethoxylate" or GEO or PEG or dimethylsiloxane or "ethylene oxide" or DMSiOEO or "polyethylene oxide" or "octylphenol polyethylene oxide" or "nonylpheno polyethylene oxide") and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 17:42			0
12	BRS	7	("glycerol propoxylate" or GPO or "polyoxyethylene lauryl ether" or "polyethylene cetyl ether" or DCA or diethylcyclohexylamine or polyethyleneimine or PEI) and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 18:04			0
13	BRS	34	("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum) same abrasive	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 18:52			0
14	BRS	24342	triazole or benzotriazole and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 18:31			0
15	BRS	38	(triazole or benzotriazole) and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 18:42			0
16	BRS	0	PEG and (("chemical mechanical polishing" or planariz\$5 or cmp) same (Cu or copper) same (Ta or TaN or tantalum))	USPAT; EPO; JPO; DERWENT; IBM TDB	2002/01/26 18:42			0